

Tool ID: 116  
Tool Location: 103

Equipment Information Sheet

# CMOS P+ Polysilicon - D4

**Manager: Phil Infante 607-254-4926**

**Backup: Aaron Windsor 607-254-4831**

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

**SAFETY**

- The furnaces are run at elevated temperatures of 400-1200°C and use flammable, toxic, and corrosive gases.

**USAGE RESTRICTIONS**

- No changing of gas flows or process parameters without staff approval
- Max process temperature of 650 C

**SCHEDULING/SIGN-UP RESTRICTIONS**

*Minimum Tool Time: 90 minutes*

- Reservation blocks greater than 8 hrs must be cleared by a MOS staff person prior to reserving the time

**MATERIALS COMPATIBILITY CATEGORY**

Tool Category 1:Restricted Silicon Based Materials Only	
Allowed	Not Allowed
Silicon Based Materials only (Si, SiC, SiO <sub>2</sub> substrates)	No Evaporated, Sputtered, or Spin on Films
All Furnace grown or deposited films	No ALD films
PECVD Films	No Metal or Organic Films
	No Glass Substrates
	No III/V Compound Semiconductors
	No Deep Silicon Etched Samples (versaline, Unaxis)
	No Organic/Biology Molecules prepared-with or without Salt buffers

**Additional Material Restrictions and Exceptions**

- MOS CLEAN required prior to use
- Only use designated MOS holders, wands and tweezers

*Last Updated: 03/20/2019*